Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model **[List multiple models if applicable.]**
ProCurve Acess Control Server 745wl (J9038A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	**Notes**	**Quantity of items included in product**
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	7
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		10
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Pozidriv screwdrivers	1Pt, 2Pt
Wire stripper/cutter	n/a
Phillips screwdriver	P0
Torx Screw Driver	T-8
Flat scredriver	3/16"

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove front bezel panel by manually grasping left and right side of panel and pulling it out
2. Using a 1Pt pozidriv screwdriver, remove all 5 screws securing top cover to chassis.. Slighly slide back top cover to release it from chassis. Remove cover.
3. Remove power supply by removing 4 pozidriv screws attaching power supply to back side of chasis (Use 2Pt pozidriv screwdrive .
4. Remove 4 phillips screws (P0) on the power supply chassis and remove top plate.
5. Using a wire cutter cut off all internal cables from power supply.
6. Remove 4 Phillips screws (using a P1 screwdrive) attaching fan to power supply chassis. Remove fan.
7. Remove 2 phillips screws (using a P1 screwdriver) attaching power connector to power supply chassis. Remove connector.
8. Unscrew 4 Posidriv screws attaching Power Supply main PCA to Power Supply Chassis. Remove PCA
9. Remove large electrolitic capacitor from Power Supply main PCA.
10. Remove Hard Disk drive assemply bracket by removing 4 Posidriv screws (1pt) attaching bracket to main chassis
11. Disconnect or cut cables going to Hard Disk Assembly
12. Remove 4 Phillips screws (use P1 screwdriver) attaching hard disk to hard disk mounting bracket. Remove Hard disk
13. Unscrew 4 Torx screws (use T-8 screw driver) attaching small PCA to bottom of Hard Disk
14. Remove 4 phillips screws (P1) from back side of main chassis attaching fan assembly to chassis. Remove additional 24 phillips screws (using P1 screwdriver) attaching all three fans to fan mounting bracket and fan screens
15. Using a 3/16" flat screwdriver, unscrew and remove 2 screws attaching large heat sink to mother board. remove heat sink. Remove fan attached to heat sink by unscrewing 4 phillips screws. Use a P0 screwdriver. Cut wires from heatsink to mother board.
16. Remove 4 Pozidriv screws attaching small PCA LCD assembly to the front main chassis. Access screws from the inside of chassis. Use 1Pt screwdriver. Cut off wires. Remove PCA.
17. Remove 12 Pozidriv screws attaching mother board to chassis. Use a 2Pt screwdriver. Remove Main PCA motherboard. Remove 8 large capacitors from mother board. Cut off or disconnect all wires going to mother board.Remove the 2 small memory boards (PCAs).
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24.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).